2N5064

GENERAL DESCRIPTION

Glass passivated sensitive gate thyristor in a plastic envelope, intended for use in general purpose switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integreated circuits and other low power gate trigger circuits.

PINNING - TO92 variant

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{DRM} ,	Repetitive peak off-state voltages	200	V
V _{RRM} I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	0.5 0.8 10	A A A

PIN CONFIGURATION

SYMBOL

PIN	DESCRIPTION	
1	anode	
2	gate	
3	cathode	
		 3 2 1



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{\text{drm}}, V_{\text{rrm}}$	Repetitive peak off-state voltages		-	200	V
I _{T(AV)}	Average on-state current	half sine wave T _c ≤ 67 °C T _c ≤ 102 °C	-	0.51 0.255	A A
I _{T(RMS)} I _{TRM}	RMS on-state current Repetitive peak on-state current	all conduction angles	-	0.8 8	A A
I _{TSM}	Non-repetitive peak on-state current	half sine wave; $T_a = 25 \degree C$ prior to surge; with reapplied $V_{DRM(max)}$; t = 8.3 ms	-	10	А
l ² t	I ² t for fusing	t = 8.3 ms	-	0.4	A ² s
I _{GM} V _{GM}	Peak gate current Peak gate voltage	T _a = 25°C, t _p = 300μs; f = 120 Hz	-	1 5	A V
V _{RGM} P _{GM}	Peak reverse gate voltage Peak gate power	$T_a = 25^{\circ}C$	-	5 0.1	V W
$\begin{array}{c} P_{G(AV)}^{G(AV)}\\ T_{stg}\\ T_{j} \end{array}$	Average gate power Storage temperature Operating junction temperature	$T_a^{-} = 25^{\circ}C$, over any 16 ms period	- -65 -65	0.01 150 125	°℃ ℃

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-c}	Thermal resistance junction to case	see note: ¹	-	-	75	K/W
R _{th j-a}	Thermal resistance junction to ambient		-	200	-	K/W

STATIC CHARACTERISTICS

 $T_c = 25$ °C, $R_{GK} = 1 \text{ k}\Omega$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$T_c = 25$ °C	-	-	200	μA
		$T_{c}^{c} = -65 \ ^{\circ}C$ $V_{D} = V_{DRM(max)}; R_{L} = 100 \ \Omega; gate open$	-	-	350	μΑ
		circuit				
l I _L	Latching current	$V_{\rm D}$ = 12 V; $R_{\rm GK}$ = 1 k Ω	-	-	6	mA
I _H	Holding current	$V_D = 12 \text{ V}; \text{ R}_{GK} = 1 \text{ k}\Omega$	-	-	5	mA
I _H V _T	On-state voltage	$I_{T} = 1.2 \text{ A peak; } t_{p} = 300 \mu\text{s; } \delta \le 0.01$	-	-	1.7	V
V _{GT}	Gate trigger voltage	$T_j = 25 \degree C_j$	-	-	0.8	V
		$T_{j} = -65 \ ^{\circ}C$	-	-	1.2	V
		T _j = 125 °C	0.1	-	-	V
		$V_{\rm D} = V_{\rm DRM(max)}$; R _L = 100 Ω ; gate open				
		circuit				
I _D , I _R	Off-state leakage current	$V_{D} = V_{D_{RM(max)}}; V_{R} = V_{RRM(max)}$ $T_{i} = 25 C$				
		$T_{j} = 25 \ C_{j}$	-	-	10	μA
		T _j = 125 °C	-	-	50	μΑ

DYNAMIC CHARACTERISTICS

 $T_c = 25$ °C, $R_{GK} = 1 \text{ k}\Omega$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform; $R_{GK} = 1 k\Omega$	-	25	-	V/µs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 2 \text{ A}; V_D = V_{DRM(max)}; I_G = 10 \text{ mA};$ $dI_C/dt = 0.1 \text{ A/us}$	-	2	-	μs
t _q	Circuit commutated turn-off time	$V_{DM}^{\circ} = 67\% V_{DRM(max)}^{\circ}; T_j = 125 ^{\circ}C;$ $I_{TM} = 1.6 A; V_R = 35 V; dI_{TM}/dt = 30 A/\mu s;$ $dV_D/dt = 2 V/\mu s; R_{GK} = 1 k\Omega$	-	100	-	μs

¹ This measurement is made with the case mounted "flat side down" on a heatsink and held in position by means of a metal clamp over the curved surface.

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MECHANICAL DATA



Notes 1. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				
Where application information is given, it is advisory and does not form part of the specification.				

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